

Attorney Reference: 126483-06085603

Client Reference: OS060008/HWL

**DECLARATION AND POWER OF ATTORNEY  
RULE 63 (37 C.F.R. 1.63) FOR PATENT APPLICATION  
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the **INVENTION ENTITLED:**  
**METHOD FOR HANDOVER BETWEEN ASYNCHRONOUS COMMUNICATION NETWORK AND SYNCHRONOUS COMMUNICATION NETWORK**

the specification of which: (check one applicable box)

A. ☐ is attached hereto.B. ☒ was filed on July 6, 2006 as U.S. Application No.          /         C. ☐ was filed as PCT International Application No. PCT/          on         and (if applicable to U.S. or PCT application) was amended on         

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56. Except as noted below, I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT International Application which designated at least one other country than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT International Application, filed by me or my assignee disclosing the subject matter claimed in this application and having a filing date (1) before that of the application on which priority is claimed, or (2) if no priority claimed, before the filing date of this application:

**PRIOR FOREIGN APPLICATION(S)**

| <u>Application/Patent Number</u> | <u>Country</u>    | <u>Day/Month/Year filed</u> | <u>Date first laid open/published</u> | <u>Patent/Grant date</u> | <u>No priority claimed</u> |
|----------------------------------|-------------------|-----------------------------|---------------------------------------|--------------------------|----------------------------|
| 10-2004-0000714                  | Republic of Korea | 06/01/2004                  |                                       |                          |                            |
|                                  |                   |                             |                                       |                          |                            |
|                                  |                   |                             |                                       |                          |                            |

If more prior foreign applications, X box at bottom and continue on attached page.

Except as noted below, I hereby claim domestic priority benefit under 35 U.S.C. 119(e) or 120 and/or 365(c) of the indicated United States applications listed below and PCT international applications listed above or below and, if this is a continuation-in-part (CIP) application, insofar as the subject matter disclosed and claimed in this application is in addition to that disclosed in such prior applications, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56 which became available between the filing date of each such prior application and the national or PCT international filing date of this application:

**PRIOR U.S. PROVISIONAL, NONPROVISIONAL AND/OR PCT APPLICATION(S)**

| <u>Application Number</u> | <u>Day/Month/Year filed</u> | <u>Status (pending/abandoned/patented)</u> | <u>No priority claimed</u> |
|---------------------------|-----------------------------|--|----------------------------|
| PCT/KR2005/000023         | 05/01/2004                  | Pending                                    |                            |
|                           |                             |  |                            |

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon;

And I hereby appoint Mayer Brown Rowe & Maw LLP, Intellectual Property Group (to whom all communications are to be directed), and persons of that firm who are associated with USPTO Customer No. 43569, as set forth below, individually and collectively, as my counsel to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and with the resulting patent, and I hereby authorize them to delete from that Customer Number the names of persons no longer with their firm, to add new persons of their firm to that Customer Number, and to act and rely on instructions from and communicate directly with the person/assignee/attorney/firm/ organization who/which sends/sent this case to them and by whom/which I hereby declare that I have consented after full disclosure to be represented unless/until I instruct the above firm and/or an attorney of that firm in writing to the contrary.

**USE ONLY FOR  
MAYER BROWN ROWE & MAW LLP  
WASHINGTON, D.C.**

\*000043569\*

(Customer No. for communications)

(1) INVENTOR'S SIGNATURE: X

Date: X

|                 |  |                        |
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| Name            | Young-Lak  | KIM                    |
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| Residence       | Yongin-si, Gyeonggi-do   | Republic of Korea      |
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(2) INVENTOR'S SIGNATURE: X

Date: X

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|-----------------|--|------------------------|
| Name            | Sung-Ho  | SHIN                   |
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☒ FOR ADDITIONAL INVENTORS, see attached page.☐ See additional foreign priorities on attached page (incorporated herein by reference).

**DECLARATION AND POWER OF ATTORNEY (continued)**  
**ADDITIONAL INVENTORS:**

**(3) INVENTOR'S SIGNATURE:   X**

**Date:   X**

|                 |  |                       |                        |
|-----------------|--|-----------------------|------------------------|
| Name            | Jong-Tae   | IHM                   |                        |
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**(4) INVENTOR'S SIGNATURE:**

**Date:**

|                 |       |                       |                        |
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| Name            |       |                       |                        |
|                 | First | Middle Initial        | Family Name            |
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**(5) INVENTOR'S SIGNATURE:**

**Date:**

|                 |       |                       |                        |
|-----------------|-------|-----------------------|------------------------|
| Name            |       |                       |                        |
|                 | First | Middle Initial        | Family Name            |
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| Mailing Address |       |                       |                        |

**(6) INVENTOR'S SIGNATURE:**

**Date:**

|                 |       |                       |                        |
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|                 | City  | State/Foreign Country | Country of Citizenship |
| Mailing Address |       |                       |                        |

**(7) INVENTOR'S SIGNATURE:**

**Date:**

|                 |       |                       |                        |
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**(8) INVENTOR'S SIGNATURE:**

**Date:**

|                 |       |                       |                        |
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| Residence       |       |                       |                        |
|                 | City  | State/Foreign Country | Country of Citizenship |
| Mailing Address |       |                       |                        |

**(9) INVENTOR'S SIGNATURE:**

**Date:**

|                 |       |                       |                        |
|-----------------|-------|-----------------------|------------------------|
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| Residence       |       |                       |                        |
|                 | City  | State/Foreign Country | Country of Citizenship |
| Mailing Address |       |                       |                        |